



Features

- ESD/Surge protect for 4 high-speed I/O channels
- Provide ESD protection for each line to
IEC 61000-4-2 (ESD) $\pm 27\text{kV}$ (air), $\pm 25\text{kV}$ (contact)
IEC 61000-4-4 (EFT) 50A (5/50ns)
IEC 61000-4-5 (Lightning) 12A (8/20 μs)
- For operating voltage of 3.3V and below
- Low capacitance : 0.5pF typical
- Fast turn-on and low clamping voltage
- Array of ESD rated diodes with internal equivalent TVS (Transient Voltage Suppression) diode
- Solid-state silicon-avalanche and active circuit triggering technology
- **Green part**

Applications

- **High Definition Multi-Media Interface (HDMI) 1.3 & 1.4 and 2.0 version**
- **DisplayPort interface**
- **SATA and eSATA interface**
- **USB3.0**
- **V-By-One**
- **LVDS interfaces**
- Ethernet port: 10/100/1000 Mb/s
- Desktop and Notebooks PCs

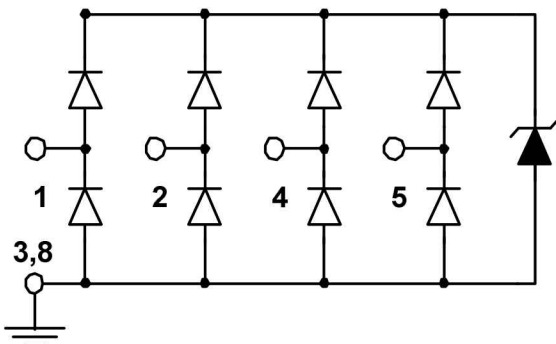
Description

AZ1243-04F is a high performance design which includes ESD rated diode arrays to protect high speed data interfaces. The AZ1243-04F has been specifically designed to protect sensitive components, which are connected to data and transmission lines, from over-voltage caused by Electrostatic Discharging (ESD), Lightning, and Cable Discharge Event (CDE).

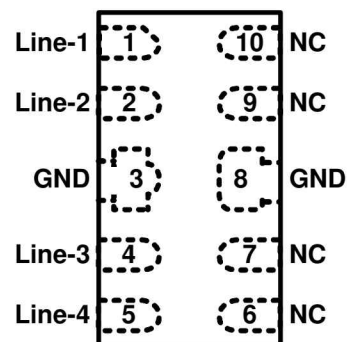
AZ1243-04F is a unique design which includes ESD rated, ultra low capacitance steering diodes and a unique design of clamping cell which is an equivalent TVS diode in a single package. During transient conditions, the steering diodes direct the transient to either the internal ESD line or to ground line. The internal unique design of clamping cell prevents over-voltage on the internal ESD line and on the I/O line, which is protecting any downstream components.

AZ1243-04F may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 ($\pm 15\text{kV}$ air, $\pm 8\text{kV}$ contact discharge).

Circuit Diagram



Pin Configuration



DFN2510P10E (Top View)

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)			
PARAMETER	SYMBOL	RATING	UNITS
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{PP} (Note 1)	12	A
Operating Voltage (I/O pin-GND)	V_{DC}	3.6	V
ESD per IEC 61000-4-2 (Air)	V_{ESD-1}	27	kV
ESD per IEC 61000-4-2 (Contact)	V_{ESD-2}	25	
Lead Soldering Temperature	T_{SOL}	260 (10 sec.)	$^\circ\text{C}$
Operating Temperature	T_{OP}	-55 to +125	$^\circ\text{C}$
Storage Temperature	T_{STO}	-55 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Reverse Stand-Off Voltage	V_{RWM}	Pin-1,-2,-4,-5 to pin-3,-8, $T = 25^\circ\text{C}$.			3.3	V
Channel Leakage Current	$I_{CH-Leak}$	$V_{Pin-1,-2,-4,-5} = 3.3\text{V}$, $V_{Pin-3,-8} = 0\text{V}$, $T = 25^\circ\text{C}$.			1	μA
Reverse Breakdown Voltage	V_{BV}	$I_{BV} = 1\text{mA}$, $T = 25^\circ\text{C}$, Pin-1,-2,-4,-5 to pin-3,-8.	4.5		7.5	V
Forward Voltage	V_F	$I_F = 15\text{mA}$, $T = 25^\circ\text{C}$, pin-3,-8 to pin-1,-2,-4,-5.	0.6		1.2	V
Lightning Clamping Voltage (Note 1)	$V_{CL-surge}$	$I_{PP} = 5\text{A}$, $t_p = 8/20\mu\text{s}$, $T = 25^\circ\text{C}$, I/O pin to GND.		5.5		V
ESD Clamping Voltage (Note 2)	V_{clamp}	IEC 61000-4-2 +8kV ($I_{TLP} = 16\text{A}$), Contact mode, $T = 25^\circ\text{C}$, I/O pin to GND.		8.5		V
ESD Dynamic Turn on Resistance	$R_{dynamic}$	IEC 61000-4-2 0 ~ +8kV, $T = 25^\circ\text{C}$, Contact mode, I/O pin to GND.		0.22		Ω
Channel Input Capacitance	C_{IN}	$V_{pin-3,-8} = 0\text{V}$, $V_{IN} = 1.65\text{V}$, $f = 1\text{MHz}$, $T = 25^\circ\text{C}$, any I/O pin to GND.		0.5	0.65	pF
Channel to Channel Input Capacitance	C_{CROSS}	$V_{pin-3,-8} = 0\text{V}$, $V_{IN} = 1.65\text{V}$, $f = 1\text{MHz}$, $T = 25^\circ\text{C}$, between I/O pins.		0.06	0.1	pF

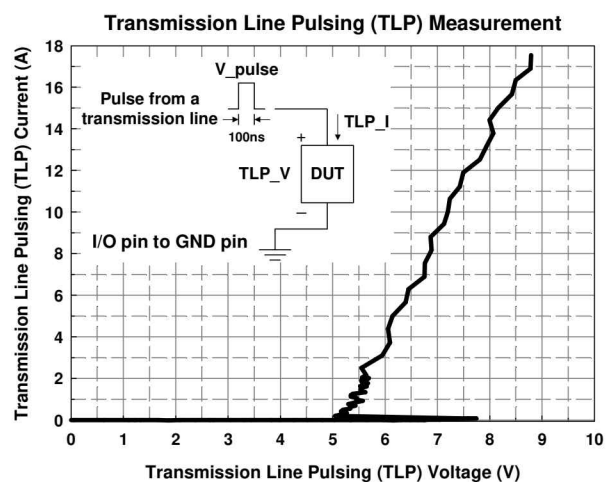
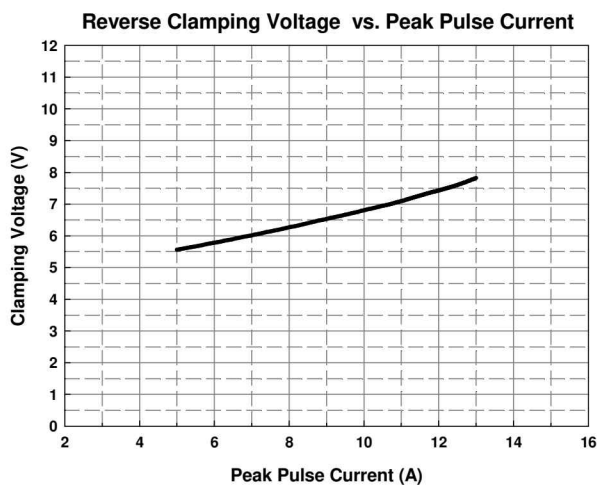
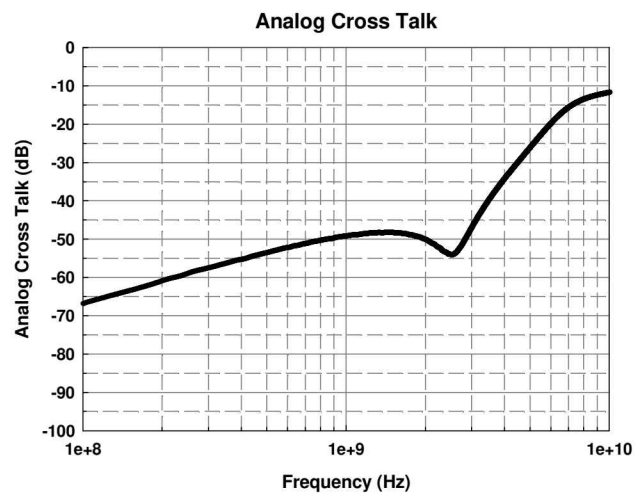
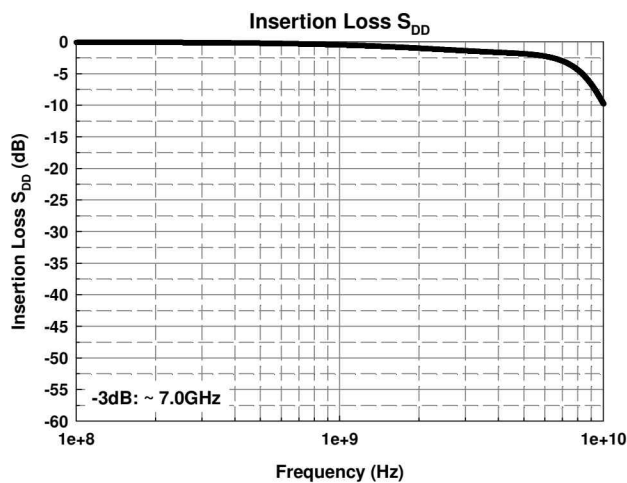
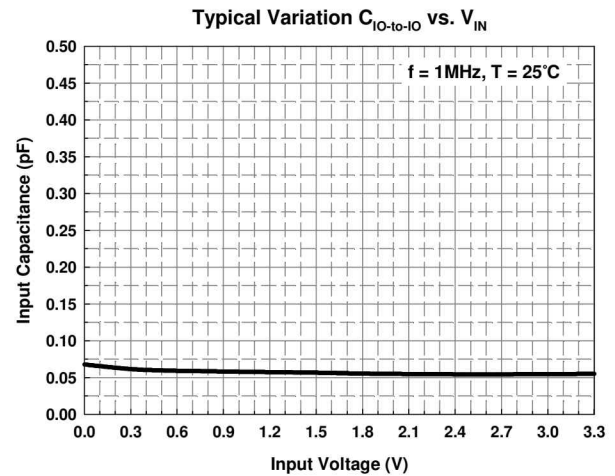
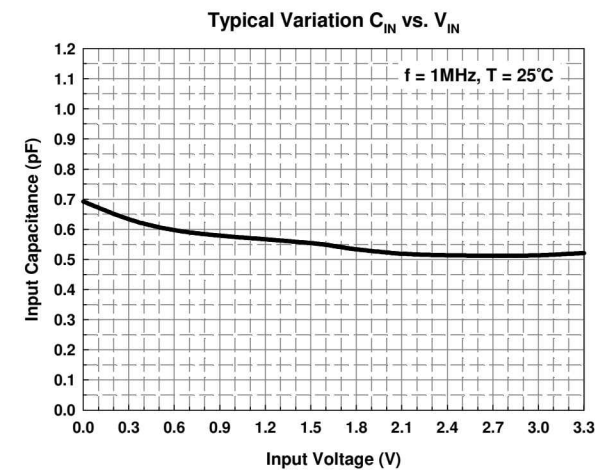
Note 1: The Peak Pulse Current measured conditions: $t_p = 8/20\mu\text{s}$, 20hm source impedance.

Note 2: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.

TLP conditions: $Z_0 = 50\Omega$, $t_p = 100\text{ns}$, $t_r = 1\text{ns}$.

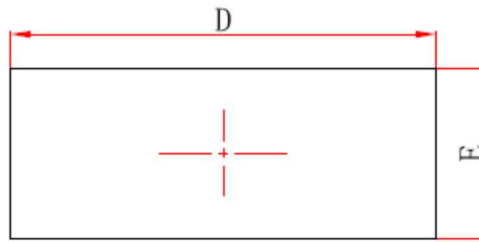


Typical Characteristics

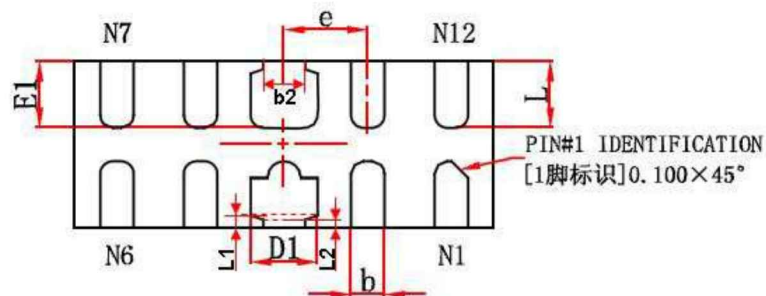




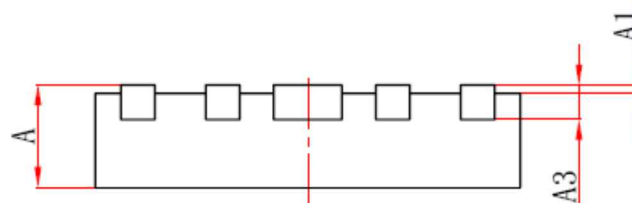
PACKAGE OUTLINE (DFN2510P10E)



TOP VIEW (unit in mm)



BOTTOM VIEW (unit in mm)

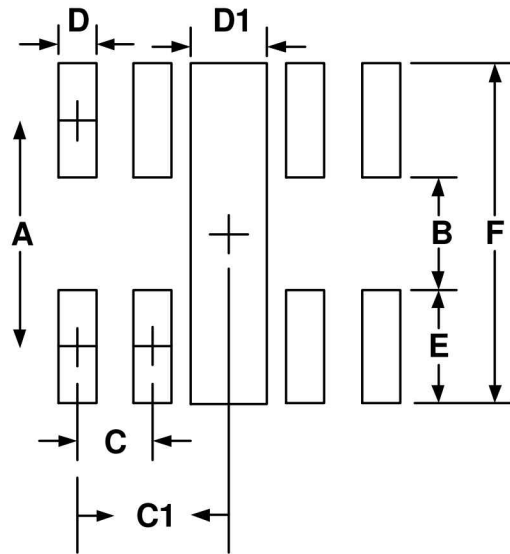


SIDE VIEW (unit in mm)

Symbol	Millimeters		Inches	
	min	max	min	max
A	0.40	0.55	0.016	0.022
A1	0.00	0.05	0.000	0.002
A3	0.152REF.		0.006 BSC	
D	2.45	2.55	0.096	0.100
E	0.95	1.05	0.037	0.041
D1	0.35	0.45	0.014	0.018
E1	0.35	0.45	0.014	0.018
b	0.15	0.25	0.006	0.010
e	0.5 BSC		0.019 BSC	
L1	0.075 REF		0.0029 REF	
L2	0.05 REF		0.0019 REF	
b2	0.20	0.30	0.0079	0.012
L	0.35	0.45	0.014	0.018



LAND LAYOUT



Dimensions		
Index	Millimeter	Inches
A	0.875	0.034
B	0.20	0.008
C	0.50	0.02
C1	1.00	0.039
D	0.25	0.01
D1	0.4	0.016
E	0.675	0.027
F	1.55	0.061

Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

MARKING CODE



243 = Device Code
X = Date Code
Y = Control Code

Part Number	Marking Code
AZ1243-04F.R7G (Green Part)	243XY

Note. Green means Pb-free, RoHS, and Halogen free compliant.

Ordering Information

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ1243-04F.R7G	Green	T/R	7 inch	3,000/reel	4 reels = 12,000/box	6 boxes = 72,000/carton



Revision History

Revision	Modification Description
Revision 2017/05/17	Formal Release.